PATENT ASSIGNMENT COVER SHEET

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EPAS ID: PAT3487676

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
KWANG YONG OH	08/17/2015
HO JUN BYUN	08/18/2015
HYUCK JUN KIM	08/17/2015
KI BUM NAM	08/17/2015
SU YEON KIM	08/17/2015

RECEIVING PARTY DATA

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PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	14828937

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NAME OF SUBMITTER:	HAE-CHAN PARK
SIGNATURE:	/hae-chan park/
DATE SIGNED:	08/18/2015
	This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 3
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HC Park & Associates, PLC
COUNSELORS at LAW

ASSIGNMENT SERVING AS DECLARATION PER 37 C.F.R. § 1.63(e)

As a below named inventor and Assignor, I declare that:

This assignment and declaration are directed to:

☒ The attached application entitled **LIGHT EMITTING DIODE PACKAGE AND MANUFACTURING METHOD THEREOF** having attorney docket number P6601US00("Application"), which claims priority from:
Korean Patent Application No. 10-2014-0106769, filed August 18, 2014, Korean Patent Application No. 10-2014-0112542, filed on August 27, 2014, and Korean Patent Application No. 10-2015-0076499, filed on May 29, 2015.

☐ As amended on ______________________ (if applicable);

The above-identified Application was made or authorized to be made by me.

I believe that I am the original inventor or an original joint inventor of a claimed invention in the Application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. § 1001 by fine or imprisonment of not more than five (5) years, or both.

Whereas, Assignor has invented certain new and useful processes, machines, articles of manufacture, compositions of matter, and/or improvements thereof ("Invention") disclosed in the Application,

Whereas, Assignor desires to convey all rights, titles, and interests in and to the same to:

Seoul Semiconductor Co., Ltd.
1B-25, 97-11, Sandan-ro 163beon-gil
Danwon-gu, Ansan-si
Gyeonggi-do 425-851
Republic of Korea

Seoul Semiconductor Co., Ltd. herein further referred to as ("Assignee").

Now, for valuable consideration by Assignee to Assignor, the receipt of which is hereby acknowledged, and for other good and valuable consideration, Assignee and Assignor hereby agree as follows:

Assignor hereby conveys, assigns, sells and transfers to Assignee all rights, title and interests in and to the Invention disclosed in said application and in and to any Letters Patent of the United States (US), any continuation, division, renewal, or substitute thereof, and hereby grant to Assignee the right to apply in its own name for patents or Inventor's certificates and related rights heretofore or hereafter filed for the Invention in any and all countries, including (without limitation) all rights to claim priority based thereon, all patents granted thereon and all reissues, extensions and renewals thereof.

Assignor hereby covenants that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this Assignment.

Assignor further covenants that Assignee will, upon Assignee's request, be provided promptly with all pertinent facts and documents relating to the Invention, Patent, Application and any patents granted thereon, as may be known and accessible to Assignor, and Assignor will testify as to the same in any interference, litigation or proceeding related thereto and will promptly execute and deliver to Assignee or Assignee's legal representative any and all papers, instruments or affidavits required to apply for, protect, obtain, maintain, issue, defend and enforce the Application, Patent, Invention, whether in the US or any and all foreign countries and any patents granted thereon and/or for obtaining any reissue or reissues of any patent which may be granted for the invention and perform such further acts which may be necessary or desirable to carry out the intent of this agreement as the Assignee thereof shall hereafter require and prepare at assignee's expense.

IN WITNESS WHEREOF, Inventor and Assignor has hereunto set hand and seal.

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